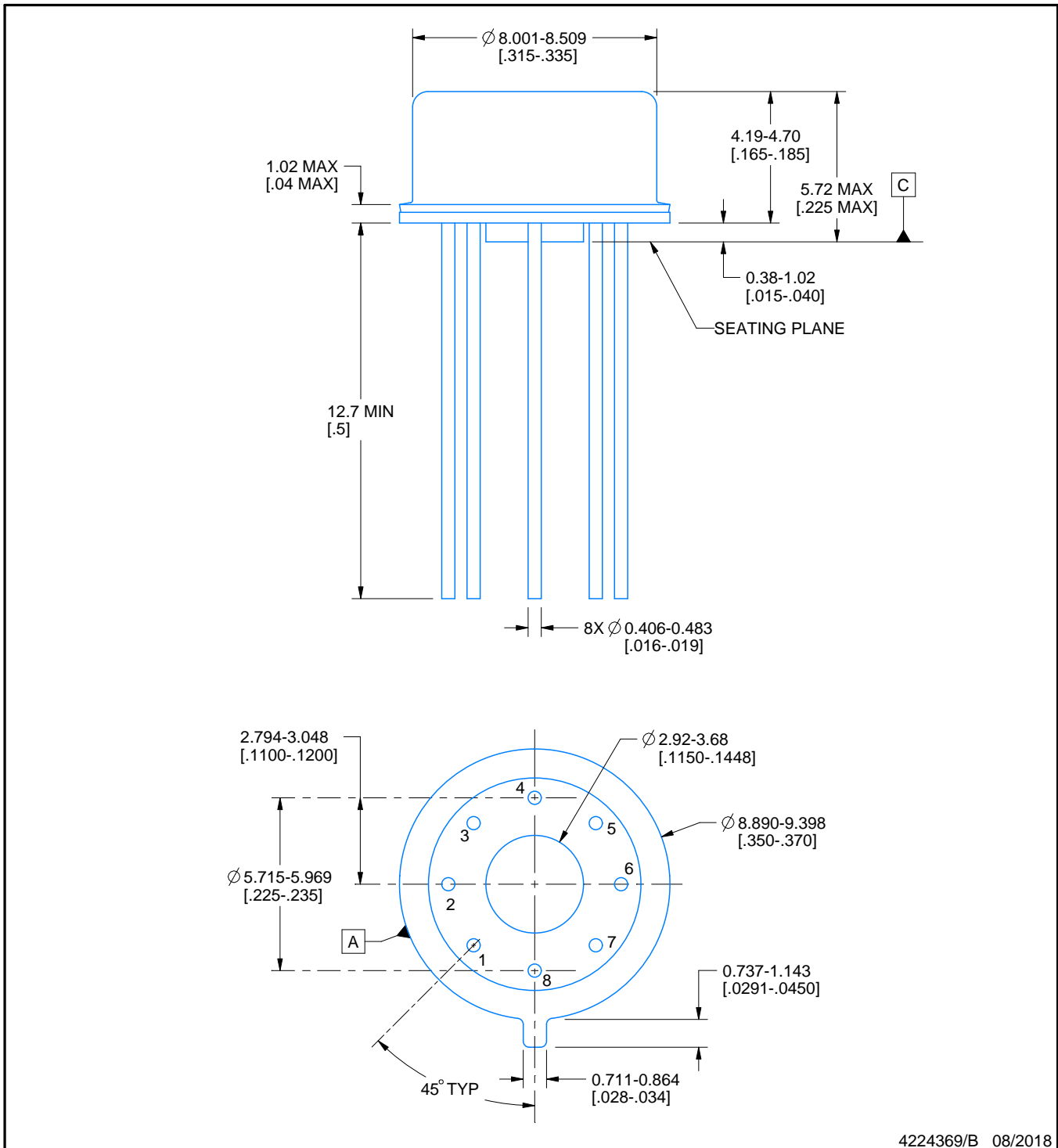


# PACKAGE OUTLINE

## LMG0008A

### TO-CAN - 5.72 mm max height

METAL CYLINDRICAL PACKAGE



#### NOTES:

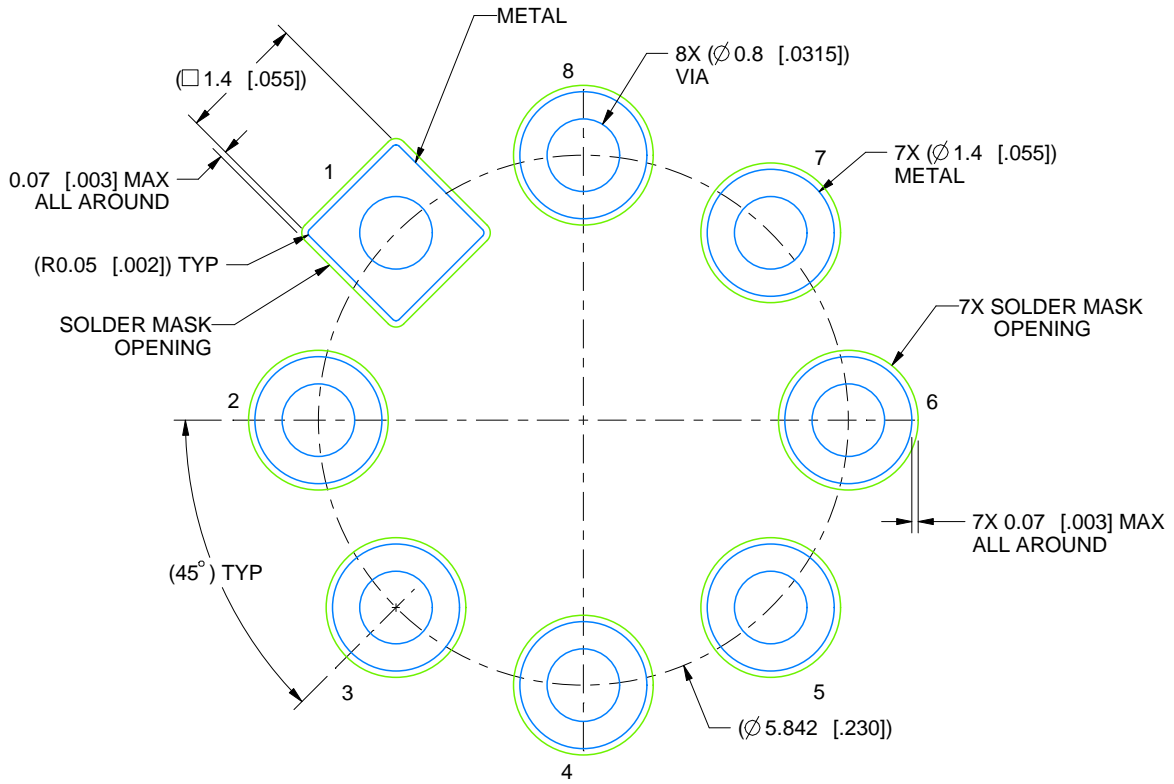
1. All linear dimensions are in millimeters [inches]. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

LMG0008A

TO-CAN - 5.72 mm max height

METAL CYLINDRICAL PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 12X

4224369/B 08/2018

# REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2174627	07/10/2018	V. DASIKA / K. SINCERBOX
B	CHANGE TO DUAL DIMENSIONING MM [INCH] FORMAT	2175848	08/17/2018	V. DASIKA / K. SINCERBOX

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